

Product End-of-Life Disassembly Instructions
Product Category: **Servers**
Marketing Name / Model
[List multiple models if applicable.]

HPE ProLiant DL385 Gen11 Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

1.3 Quantities vary by product configuration

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	11
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Quantity varies by product configuration and power supply model selected	3 to 8
External electrical cables and cords	Quantity depends on number of power supplies, networking devices, and I/O devices	1 to 14
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Item Description	Notes	Quantity of items included in product
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T-10
Torx Driver	T-15
Torx Driver	T-20
Hex socket	3/16
Screw Driver Cross Type	PH-0
Screw Driver Flat type	
Sharp Nose Pliers	
Soldering Iron	

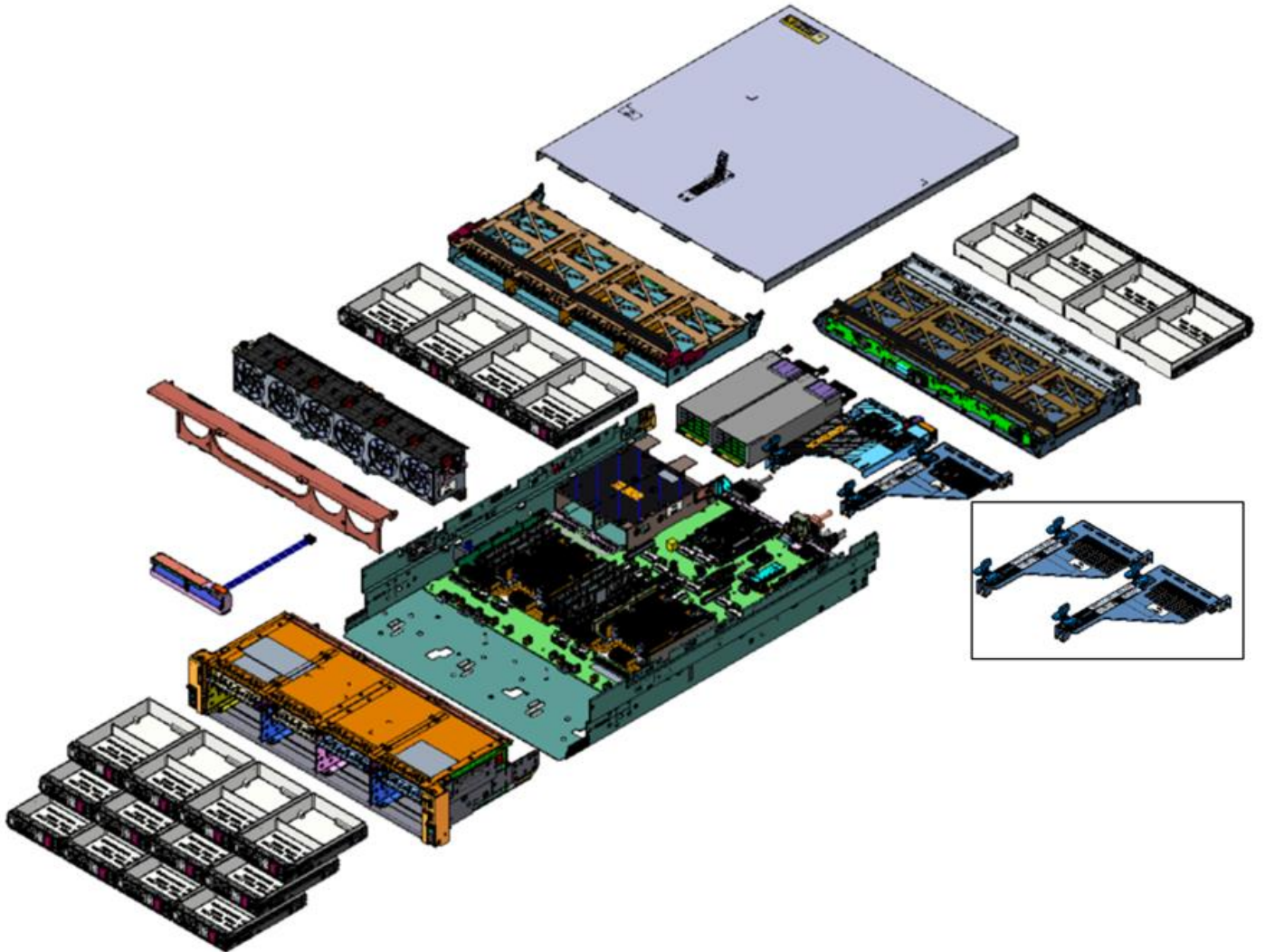
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disconnect all cables
2. Remove Fan module & fan cage
3. Remove MID cage
4. Remove 2U riser cage & riser card
5. Remove Main Board ASSY
6. Separate the Main Board and ME parts
7. Remove SFF media bay
8. Remove Rear 2SFF HDD cage
9. Remove CPU Heatsink and CPU
10. Remove RTC battery
11. Remove Megacell Battery
12. Remove Latch Ear and FIO board
13. Remove MID wall (SFF)
14. Remove Fan cage holder bracket
15. Separate the Front-end & Rear-end (SFF)
16. Remove SID blank (SFF)
17. Remove the OCP rail
18. Remove Tertiary Blank (include 2SFF blank & WM blank)
19. Remove the rear wall bracket (1U)
20. Remove the rear wall bracket (2U)

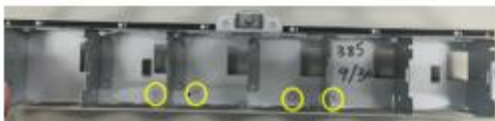
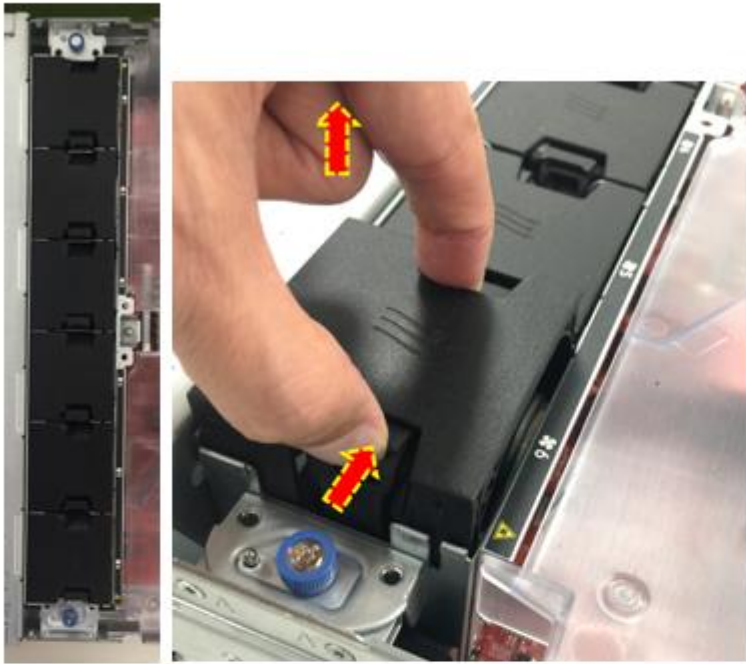
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

Attachment 1 – System exploding drawing



Attachment 2 – Remove Fan module & Fan cage

Use T-15 screwdrivers to remove the Fan cage from the chassis.



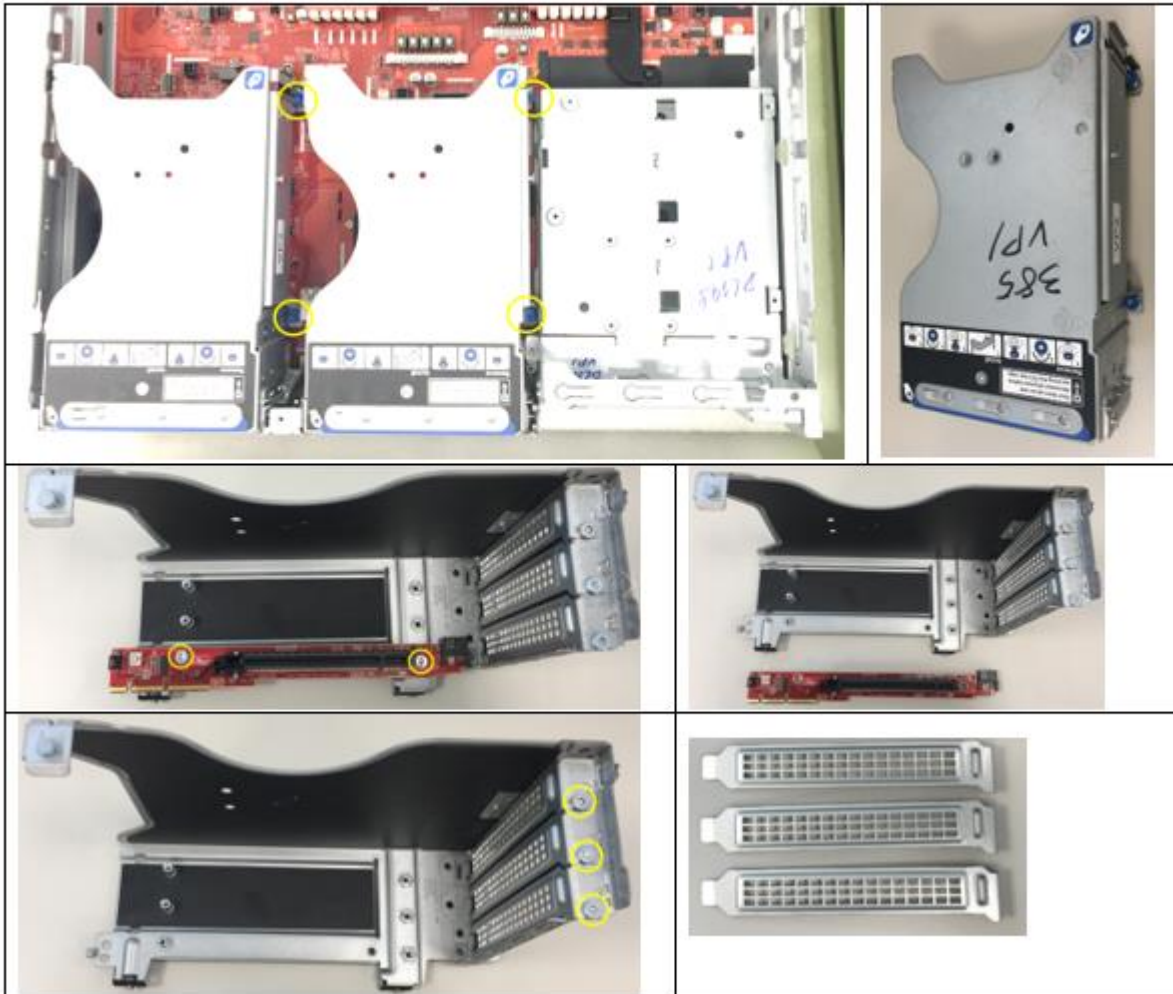
Attachment 3 – Remove MID cage

Use T-10 & T-15 screwdrivers to remove the MID cage from the chassis.



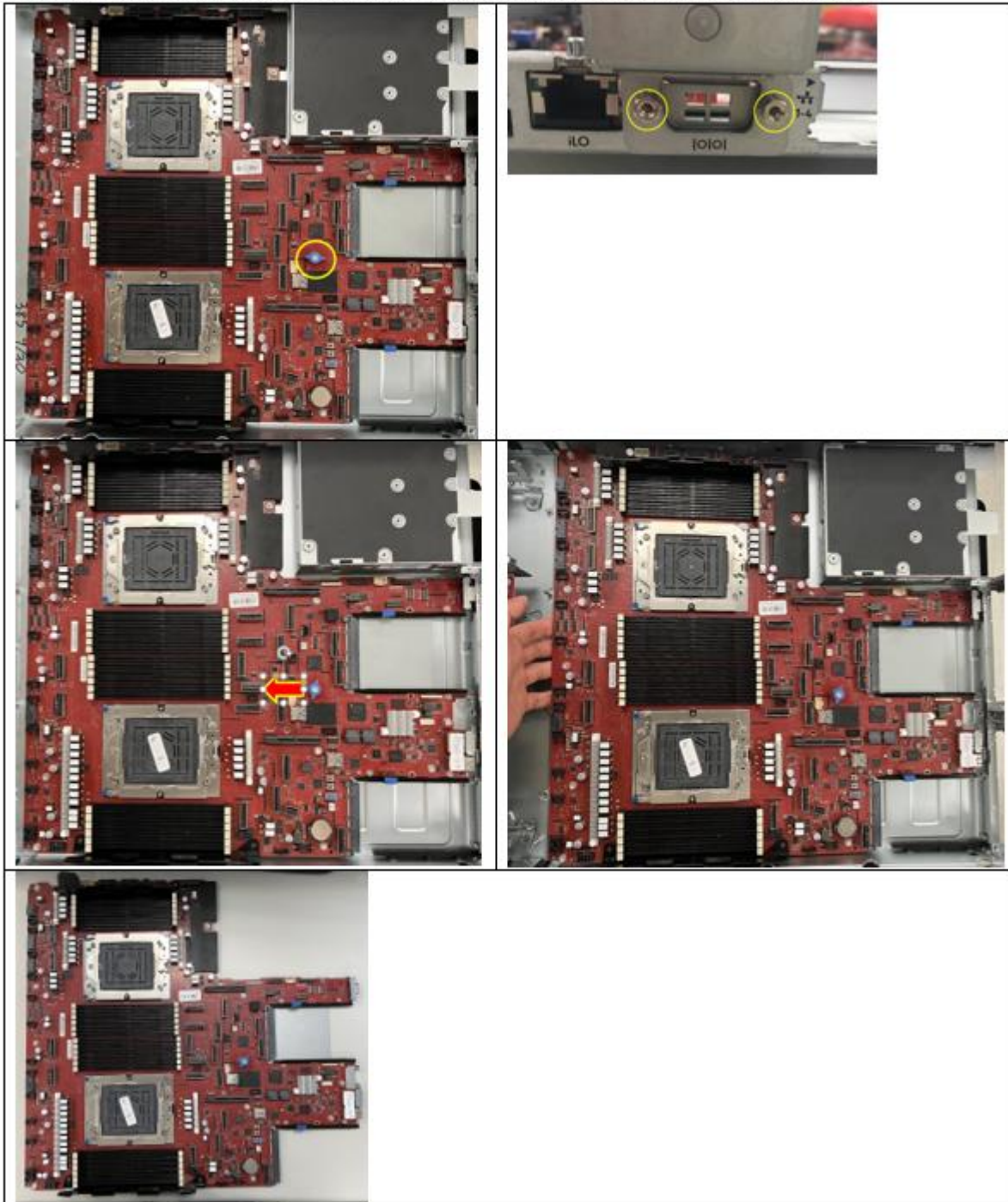
Attachment 4 - Remove 2U riser cage & riser card

Use T-10 and T-15 screwdriver to remove the 2U riser cage & riser card from the chassis.



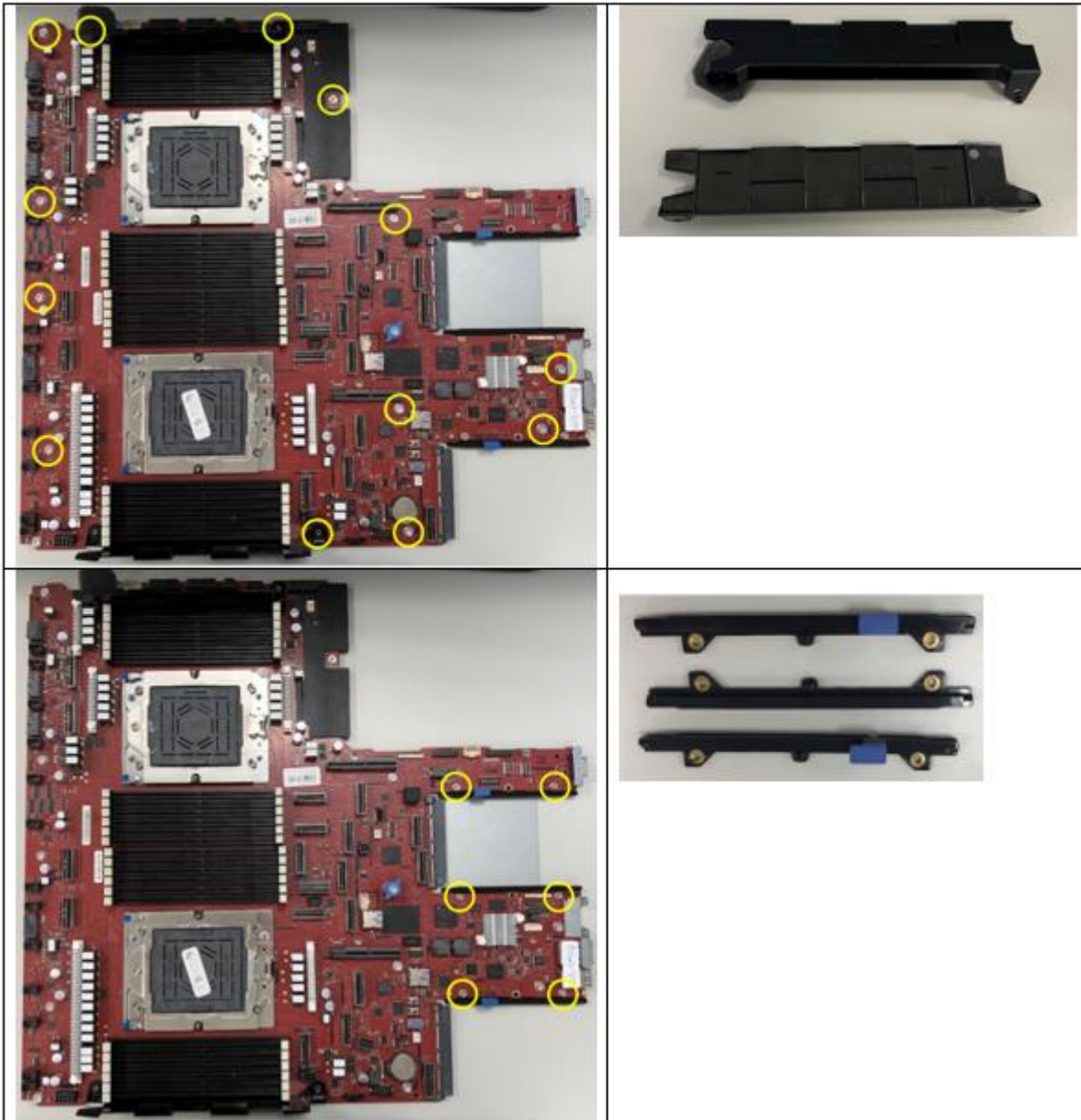
Attachment 5 - Remove Main Board ASSY

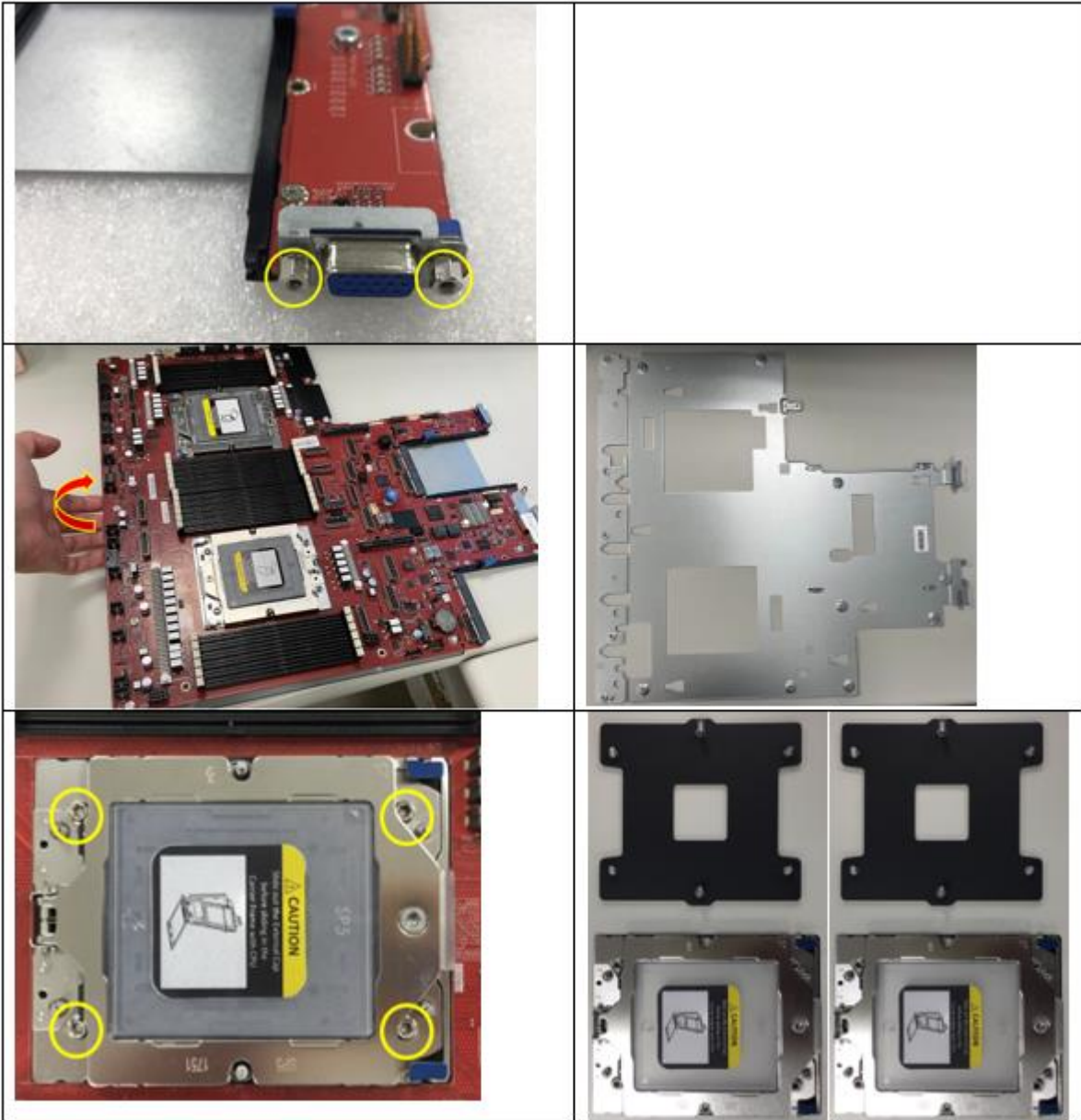
Use T-15 screwdriver and 3/16 Hex socket to remove the MB ASSY from the chassis.



Attachment 6 – Separate the Main Board and ME parts

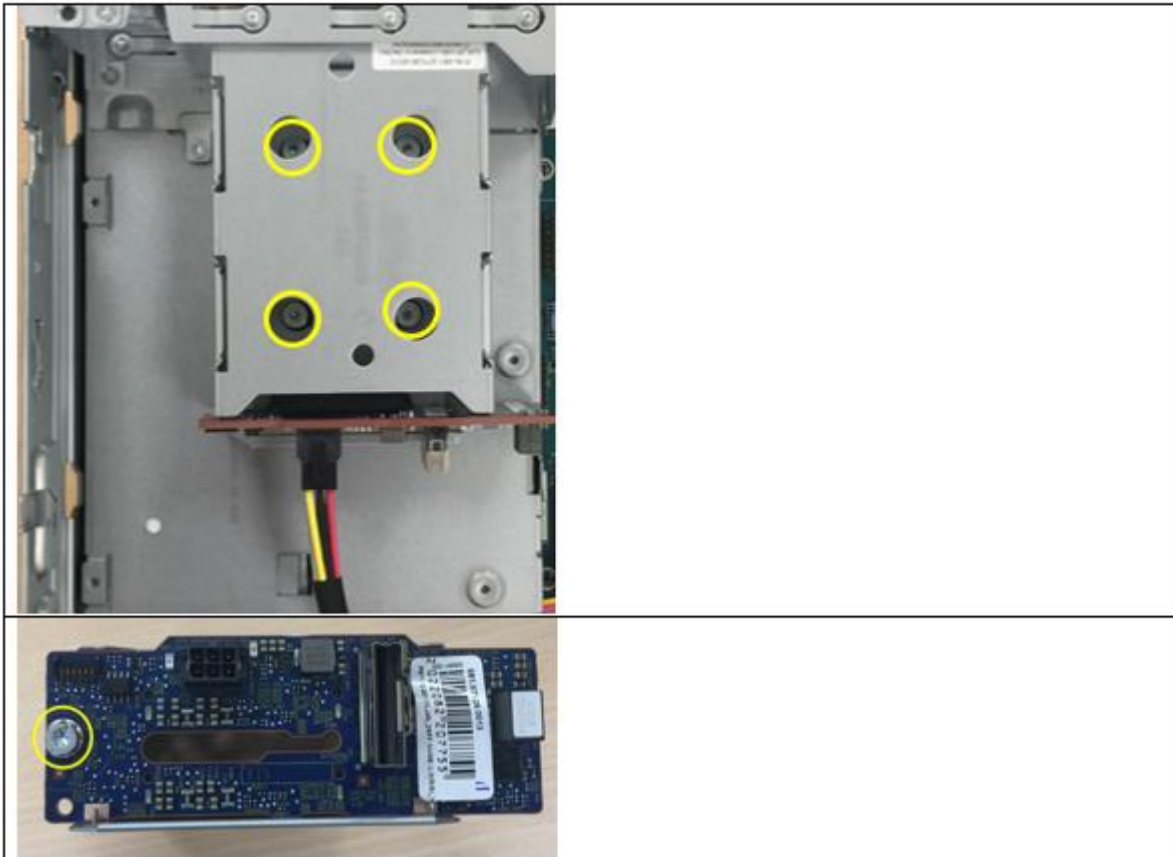
Use T-15, T-20 & PH1 screwdrivers to remove the MB ME parts.





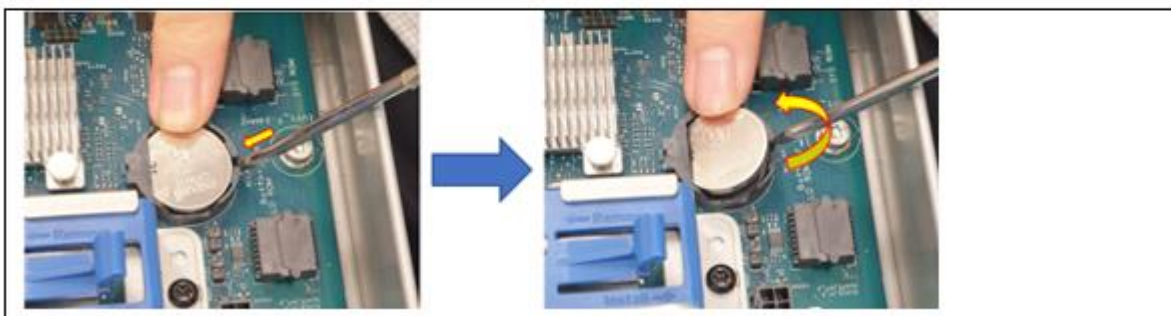
Attachment 7 – Remove Rear 2SFF HDD cage

Use T-10 & T-15 screwdrivers to remove the rear 2SFF HDD cage from the chassis.



Attachment 8 - Remove RTC battery

To remove RTC battery by pushing the latch as drawing below.

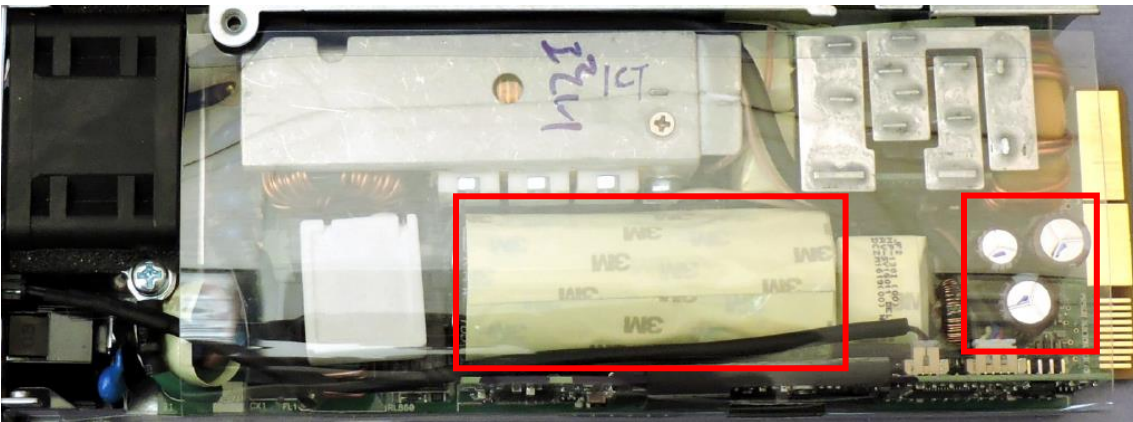


Attachment 9 – Remove Megacell



Attachment 10 – Remove Electrolytic Capacitors

1. HSTNS-PD41-1



2. HSTNS-PL41-1



3. HSTNS-PC41-1

